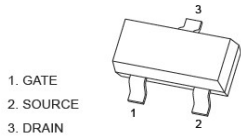


V(BR)DSS	RDS(ON)MAX	ID
-50V	8Ω@-10V	-0.13A
	10Ω@-5V	

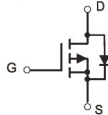
#### SOT-23



#### MARKING



#### Equivalent Circuit



## SOT-23 贴片塑封场效应管 SOT-23 Plastic-Encapsulate MOSFET

#### 特征 Features

- Energy Efficient
- Low Threshold Voltage
- High-speed Switching.
- DC/DC Converter.

#### 机械数据 Mechanical Data

- 封装: SOT-23 封装 SOT-23 Small Outline Plastic Package.
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0.
- 安装位置: 任意 Mounting Position: Any.

#### 极限值和温度特性(TA = 25°C 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
Drain-Source Voltage	V <sub>DS</sub>	-50	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	-0.13	A
Pulsed Drain Current (tp<10us) (note1)	I <sub>DM</sub>	-0.52	A
Power Dissipation	P <sub>D</sub>	225	mW
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-50-+150	°C
Thermal Resistance From Junction to Ambient (note2)	R <sub>θJA</sub>	556	°C/W
Maximum Lead Temperature for Soldering Purposes, Duration for 5 Seconds	T <sub>L</sub>	260	°C

#### 电特性 (TA = 25°C 除非另有规定)

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameter	符号 Symbols	测试条件 Test Condition	界限 Limits			单位 Unit
			Min	Typ	Max	
<b>Static</b>						
Drain-Source Breakdown Voltage	V(BR)DSS	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-50			V
Gate-Threshold voltage(note3)	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.9	-1.6	-2.0	V
Gate-body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±5	uA
Zero Gate Voltage Drain current	I <sub>DSS</sub>	V <sub>DS</sub> =-50V, V <sub>GS</sub> =0V			-15	uA
		V <sub>DS</sub> =-25V, V <sub>GS</sub> =0V			-0.1	
Drain-Source On-Resistance (note3)	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-5V, I <sub>D</sub> =-0.1A		5.8	10	Ω
		V <sub>GS</sub> =-10V, I <sub>C</sub> =-0.1A		4.5	8	
Forward trans conductance (note1)	g <sub>fs</sub>	V <sub>DS</sub> =-25V, I <sub>D</sub> =-0.1A	50			mS
Diode forward voltage	V <sub>SD</sub>	I <sub>S</sub> =0.34A, V <sub>GS</sub> =0V			1.3	V
<b>Dynamic(note4)</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> =5V, V <sub>GS</sub> =0V, f=1MHz		30		pF
Output capacitance	C <sub>oss</sub>			10		
Reverse Transfer capacitance	C <sub>rss</sub>			5		
<b>Switching(note3,4)</b>						
Turn-on Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V, R <sub>L</sub> =50Ω, I <sub>D</sub> ≈-0.25A,		2.5		ns
Rise time	t <sub>r</sub>			1		
Turn-off Time	t <sub>d(off)</sub>			16		
Fall time	t <sub>f</sub>			8		
<b>SOURCE-DRAIN DIODE CHARACTERISTICS</b>						
Continuous Current	I <sub>S</sub>				-0.13	A
Pulsed Current	I <sub>SM</sub>				-0.52	A
Diode forward Voltage (note 3)	V <sub>SD</sub>	I <sub>S</sub> =-0.13A, V <sub>GS</sub> =0V			-2.2	V

Notes: 1). Repetitive rating: Pulse width limited by junction temperature.

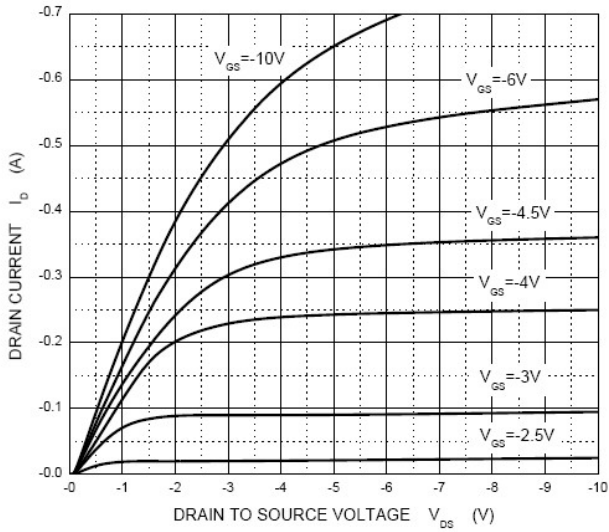
2). Surface mounted on FR4 board, t ≤ 10s

3). Pulse Test: Pulse Width ≤ 300us, Duty Cycle ≤ 2%.

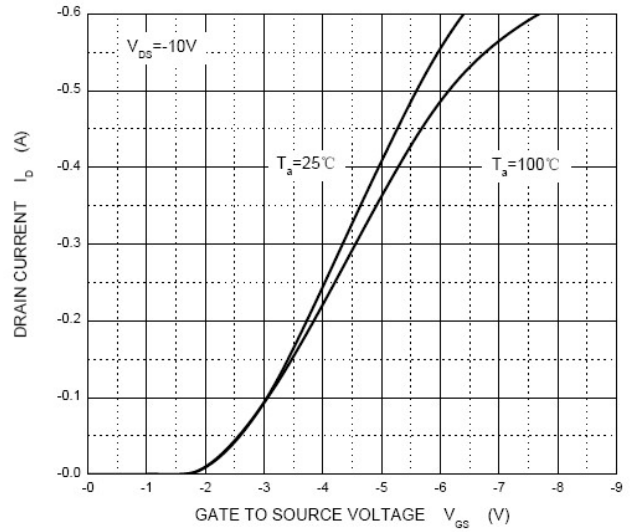
4). Guaranteed by design, not subject to producing.

## Typical characteristics

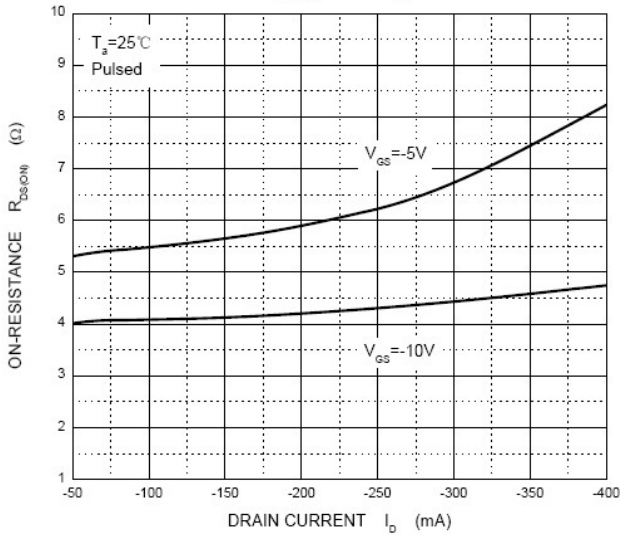
### Output Characteristics



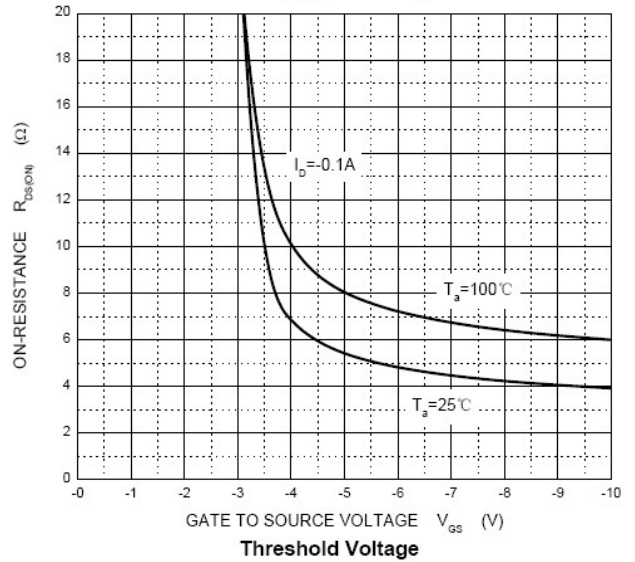
### Transfer Characteristics



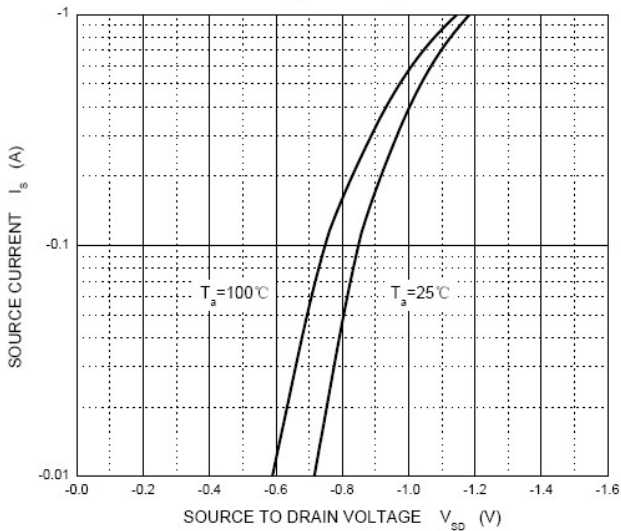
### $R_{DS(ON)}$ — $I_D$



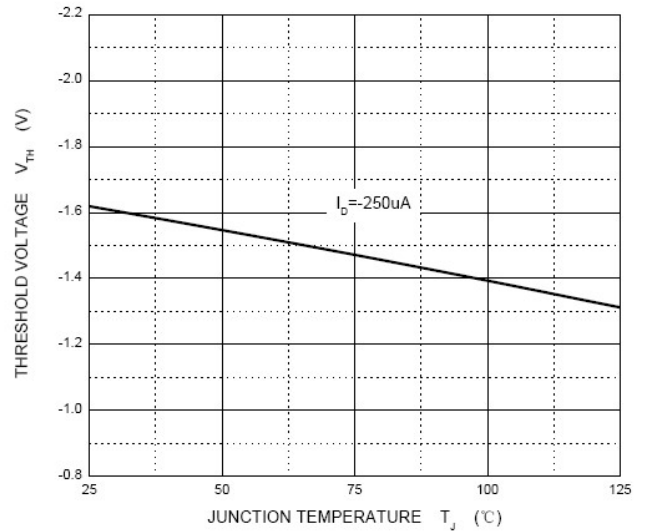
### $R_{DS(ON)}$ — $V_{GS}$



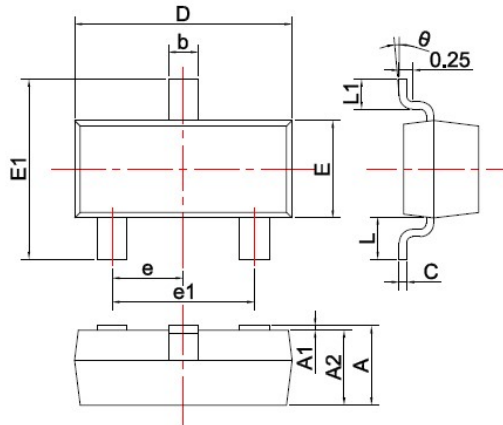
### $I_S$ — $V_{SD}$



### Threshold Voltage



## SOT-23 PACKAGE OUTLINE Plastic surface mounted package

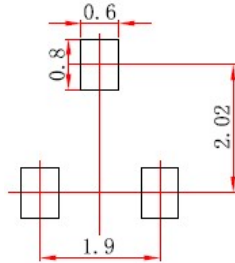


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

Unit: mm

### 焊盘设计参考 Precautions: PCB Design

Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs



#### Note:

1. Controlling dimension: In millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.